[0009a]

In another aspect, there is provided a method of producing a filtration filter, the method comprising: forming a spot face portion at a central portion of a substrate, thereby forming a thick wall portion that forms a perimeter portion of the substrate and a thin wall portion surrounded by the thick wall portion; forming a through hole that penetrates the substrate from front to back at a central portion of the thin wall portion; forming a plurality of first spacing maintaining members with a predetermined height at a predetermined interval on the thick wall portion; forming a plurality of second spacing maintaining members on the thin wall portion at a predetermined interval, each of the second spacing maintaining members having a thermal expansion coefficient larger than that of the first interval maintaining members and being longer than the first spacing maintaining members; and stacking a plurality of substrates via at least the first interval maintaining members.

[0009b]

In another aspect, there is provided a method of producing a filtration filter, comprising: forming an annular masking material along a perimeter portion of a front surface of a substrate; etching the substrate formed with the annular masking material so that a thin wall portion surrounded by a convex portion which corresponds to the annular masking material is formed; peeling a part of the masking material on the convex portion after the etching step of the substrate formed with the annular masking material is terminated; etching the substrate after the peeling step of the part of the masking material on the convex portion so that a thick wall portion is formed by the convex portion other than a portion coated with the masking material remaining after the peeling step and a

spacing maintaining portion protruding from the thick wall portion is formed by the convex portion of the portion coated with the remaining masking material; forming a through hole that penetrates the substrate from front to back at a central portion of the thin wall portion surrounded by the thick wall portion; forming a plurality of spacing maintaining members on the thin wall portion of the substrate formed with the through hole at a predetermined spacing, each of the plurality of spacing maintaining members having a thermal expansion coefficient larger than that of the spacing maintaining portion and having a height higher than that of the spacing maintaining portion; peeling the masking material from the spacing maintaining portion; and stacking a plurality of substrates at least via the spacing maintaining portion.